TPDxE05U06 适用于超高速（最高可达 6GBPS）接口的单通道、4 通道、6 通道静电放电 (ESD) 保护器件

1 特性

- IEC 61000-4-2 4 级静电放电 (ESD) 保护
  - ±12kV 接触放电
  - ±15kV 气隙放电
- IEC 61000-4-4 瞬态放电 (EFT) 保护
  - 80A (5/50ns)
- IEC 61000-4-5 浪涌保护
  - 2.5A (8/20μs)
- IO 电容范围：0.42pF 至 0.5pF（典型值）
- 直流击穿电压：6.5V（最小值）
- 超低泄漏电流：10nA（最大值）
- 低 ESD 钳位电压
- 工业温度范围：-40°C 至 +125°C
- 简易直通路由封装

2 应用

- HDMI 1.4*b*
- HDMI 2.0
- USB 3.0
- MHL
- 低压差分信令 (LVDS) 接口
- DisplayPort
- PCI-Express®
- eSata 接口
- V-by-One®HS

3 说明

TPDxE05U06 是基于单向瞬态电压抑制器 (TVS) 的静电放电 (ESD) 保护二极管产品系列，具有超低电容。每个器件的 ESD 冲击消散值高于 IEC 61000-4-2 国际标准规定的最高水平。TPDxE05U06 的超低负载电容使其非常适用于保护任何高速信号引脚。

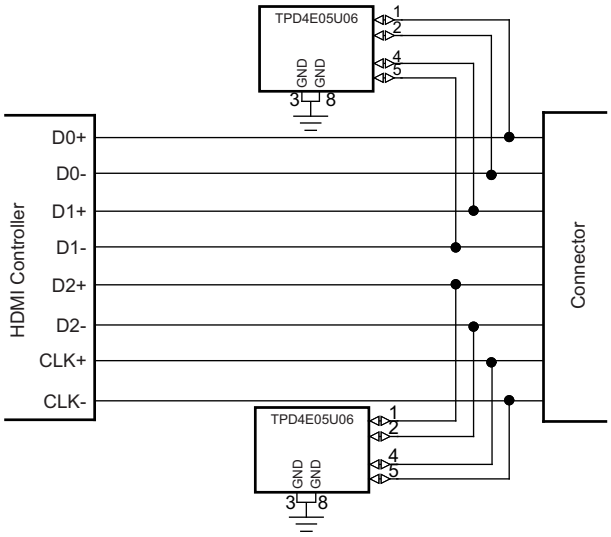
TPDxE05U06 的典型应用 包括以下产品中的信号线：HDMI 1.4*b*、HDMI 2.0、USB 3.0、MHL、LVDS、DisplayPort、 PCI Express®、eSata 和 V-by-One®HS。

器件信息(1)

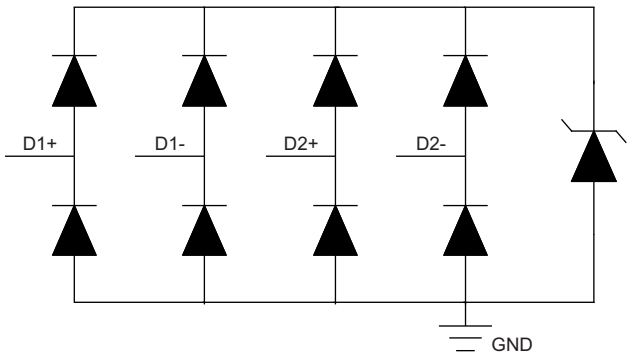
器件型号	封装	封装尺寸（标称值）
TPD1E05U06	X1SON (2)	0.60mm x 1.00mm
TPD4E05U06	USON (10)	2.50mm x 1.00mm
TPD6E05U06	USON (14)	3.50mm × 1.35mm

(1) 如需了解所有可用封装，请见数据表末尾的可订购产品附录。

简化电路原理图



TPD4E05U06 功能框图



目录

4 修订历史记录

注：之前版本的页码可能与当前版本有所不同。

Changes from Revision K (November 2016) to Revision L — **Page**

- Updated DPY pinout image. ... 4
- Updated title from TPD4E05U06 to TPD6E05U06 in Figure 13 ... 10

Changes from Revision J (March 2016) to Revision K — **Page**

- Changed min value of V_{BR} from "6 V" to "6.5 V" in the *Electrical Characteristics* table ... 7

Changes from Revision I (June 2015) to Revision J — **Page**

- 已将所有 *X2SON* 实例替换为 *X1SON* ... 1
- Update the *Pin Functions* table ... 4
- Added *Power Supply Recommendations* section ... 16

Changes from Revision H (May 2015) to Revision I — **Page**

- 已添加商标 ... 1
- Corrected TPD6E05U06 Pin 13 name ... 5
- Corrected TLP definition ... 7

Changes from Revision G (July 2014) to Revision H — **Page**

- 已添加附加应用。 ... 1
- Updated with HDMI 2.0 Eye Diagrams ... 13

Changes from Revision F (November 2013) to Revision G **Page**

- 已添加 61000-4-4 EFT 标准 1
- Added Handling Ratings table. 6
- Added Thermal Information table. 6
- Added Detailed Description section. 10
- Added Application and Implementation section. 12
- Added Layout section. 16

Changes from Original (December 2012) to Revision A **Page**

- 已添加 TPS2EUSB30A 部件到文档。 1

Changes from Revision A (December 2012) to Revision B **Page**

- Added Insertion Loss Graphic. 9
- Added Eye Diagrams. 13

Changes from Revision B (January 2013) to Revision C **Page**

- 已更改 IO 电容范围 1
- Changed test conditions and typ values for V_{clamp} 7
- Added typ R_{DYN} values for DQA and RVZ packages 7
- Added C_L values for DQA and RVZ packages 7
- Changed CURRENT vs VOLTAGE graphic 8
- Changed Insertion Loss graphic 9
- Changed HDMI Eye Diagrams 13

Changes from Revision C (March 2013) to Revision D **Page**

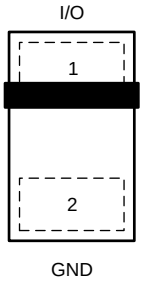
- 已更新标题。 1
- Removed Ordering Information table. 4

Changes from Revision D (August 2013) to Revision E **Page**

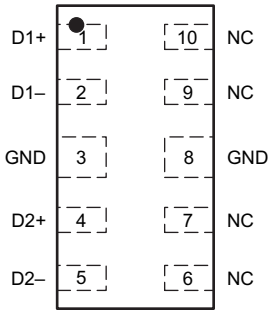
- 已更新文档格式。 1
- 已添加附加应用。 1

5 Pin Configuration and Functions

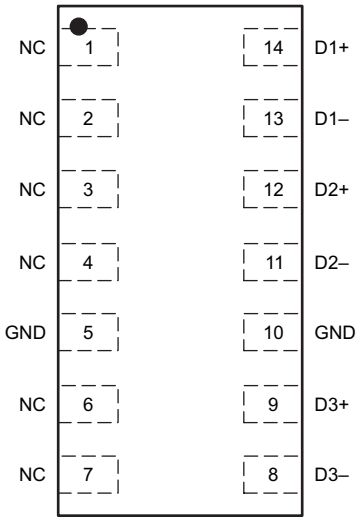
DPY Package
2-Pin X1SON
Top View



DQA Package
10-Pin USON
Top View



RVZ Package
14-Pin USON
Top View



Pin Functions TPD1E05U06 DPY

PIN		TYPE	DESCRIPTION
NAME	NO.		
GND	2	Ground	Ground; Connect to ground
I/O	1	I/O	ESD protected channel(1)

(1) Place as close to the connector as possible.

Pin Functions TPD4E05U06 DQA

PIN		TYPE	DESCRIPTION
NAME	NO.		
D1+	1	I/O	ESD protected channel(1)
D1–	2	I/O	ESD protected channel(1)
D2+	4	I/O	ESD protected channel(1)
D2–	5	I/O	ESD protected channel(1)

(1) Place as close to the connector as possible.

Pin Functions TPD4E05U06 DQA (continued)

PIN		TYPE	DESCRIPTION
NAME	NO.		
GND	3	Ground	Ground; Connect to ground
GND	8		
NC	6	—	Not connected; Used for optional straight-through routing. Can be left floating or grounded
NC	7		
NC	9		
NC	10		

Pin Functions TPD6E05U06 RVZ

PIN		TYPE	DESCRIPTION
NAME	NO.		
D1+	14	I/O	ESD protected channel(1)
D1–	13	I/O	ESD protected channel(1)
D2+	12	I/O	ESD protected channel(1)
D2–	11	I/O	ESD protected channel(1)
D3+	9	I/O	ESD protected channel(1)
D3–	8	I/O	ESD protected channel(1)
GND	5	Ground	Ground; Connect to ground
GND	10		
NC	1	—	Not connected; Used for optional straight-through routing. Can be left floating or grounded
NC	2		
NC	3		
NC	4		
NC	6		
NC	7		

(1) Place as close to the connector as possible.

6 Specifications

6.1 Absolute Maximum Ratings(1)(2)(3)

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
Electrical fast transient	IEC 61000-4-4 (5/50 ns)		80	A
Peak pulse	IEC 61000-4-5 Current (tp – 8/20 µs)(4)		2.5	A
	IEC 61000-4-5 Power (tp – 8/20 µs)(4)		40	W
T_A	Operating temperature	–40	125	°C
T_{stg}	Storage temperature	–65	155	°C

(1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) Absolute maximum ratings apply over recommended junction temperature range.
(3) Voltages are with respect to GND unless otherwise noted.
(4) Measured at 25°C.

6.2 ESD Ratings—JEDEC Specification

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	±4000	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101(2)	±1500	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process. Manufacturing with less than 500-V HBM is possible with the necessary precautions. Pins listed as ±4000 V may actually have higher performance.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process. Manufacturing with less than 250-V CDM is possible with the necessary precautions. Pins listed as ±1500 V may actually have higher performance.

6.3 ESD Ratings—IEC Specification

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	IEC 61000-4-2 contact discharge	±12000	V
		IEC 61000-4-2 air-gap discharge	±15000	

6.4 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{IO}	Input pin voltage	0	5.5	V
T_A	Operating free-air temperature	–40	125	°C

6.5 Thermal Information

THERMAL METRIC(1)		TPD1E05U06 DPY (X1SON) 2 PINS	TPD4E05U06 DQA (USON) 10 PINS	TPD6E05U06 RVZ (USON) 14 PINS	UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	697.3	327	197.9	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	471	189.5	119.1	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	575.9	257.7	92.6	°C/W
ψ_{JT}	Junction-to-top characterization parameter	175.7	60.9	22	°C/W
ψ_{JB}	Junction-to-board characterization parameter	575.1	257	91.6	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report.

6.6 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
V_{RWM}	Reverse stand-off voltage	I_{IO} < 10 µA				5.5	V
V_{BR}	Break-down voltage	I_{IO} = 1 mA		6.5		8.5	V
V_{clamp}	Clamp voltage	I = 1 A, TLP, I/O to ground(1)			10		V
		I = 5 A, TLP, I/O to ground(1)			14		
		I = 1 A, TLP, ground to I/O(1)			3		
		I = 5 A, TLP, ground to I/O(1)			7		
I_{LEAK}	Leakage current	V_{IO} = 2.5 V			0.01	10	nA
R_{DYN}	DPY package dynamic resistance	I/O to GND(2)			0.8		Ω
		GND to I/O(2)			0.8		
	DQA package dynamic resistance	I/O to GND(2)			0.8		Ω
		GND to I/O(2)			0.8		
	RVZ package dynamic resistance	I/O to GND(2)			0.8		Ω
		GND to I/O(2)			0.8		
Capacitance							
C_L	Line capacitance(3)	V_{IO} = 2.5 V, f = 1 MHz, I/O to GND	TPD1E05U06 DPY package		0.42		pF
			TPD4E05U06 DQA package		0.5		
			TPD6E05U06 RVZ package		0.47		
$\Delta C_{IO\text{-}TO\text{-}GND}$	Variation of channel input capacitance	GND Pin = 0 V, F = 1 GHz, V_{BIAS} = 2.5 V, channel_x pin to GND – channel_y pin to GND			0.05	0.07	pF
C_{CROSS}	Channel to channel input capacitance	GND Pin = 0 V, F = 1 GHz, V_{BIAS} = 2.5 V, between channel pins			0.01	0.06	pF

(1) Transmission Line Pulse (TLP) with 100 ns width, 200 ps rise time.
(2) Extraction of R_{DYN} using least squares fit of TLP characteristics between I = 10 A and I = 20 A.
(3) Capacitance data is taken at 25°C.

6.7 Typical Characteristics

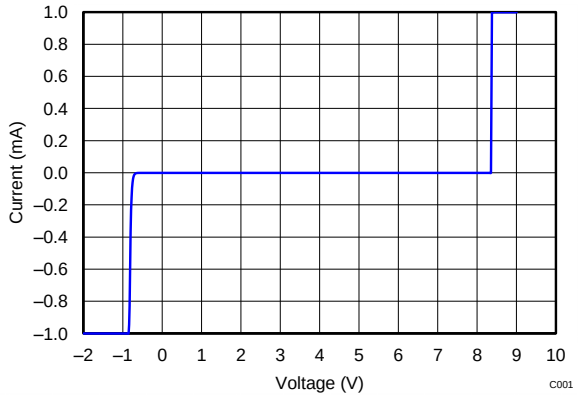


Figure 1. DC Voltage Sweep I-V Curve

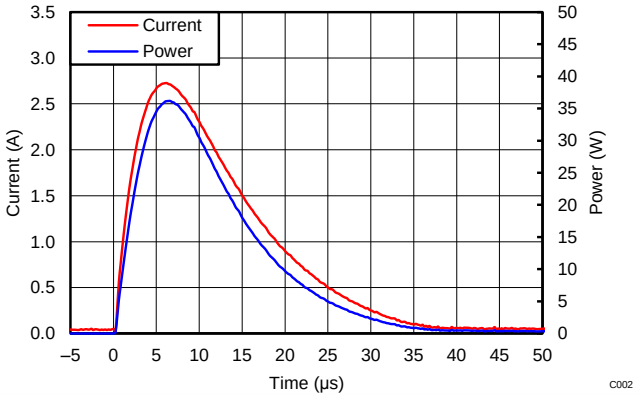


Figure 2. Surge Curve (tp = 8/20 µs), Pin IO to GND

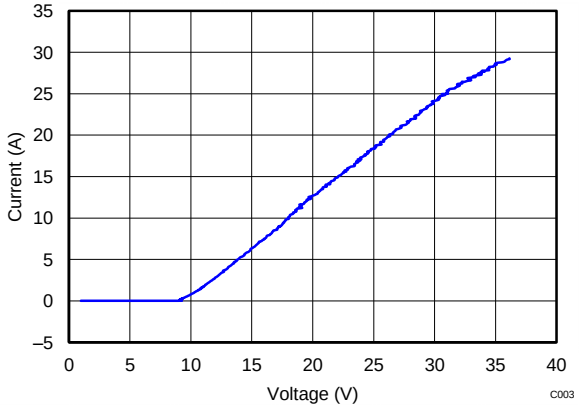


Figure 3. Positive TLP Plot IO to GND

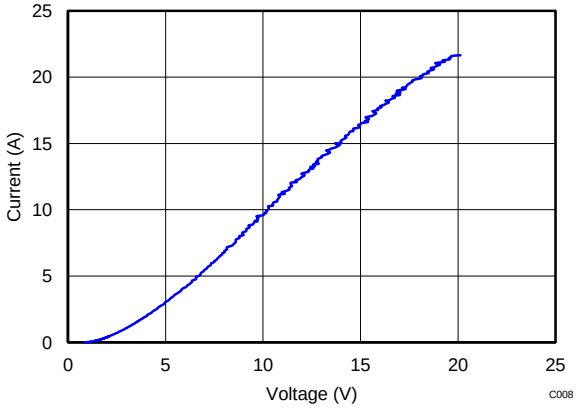


Figure 4. Negative TLP Plot IO to GND

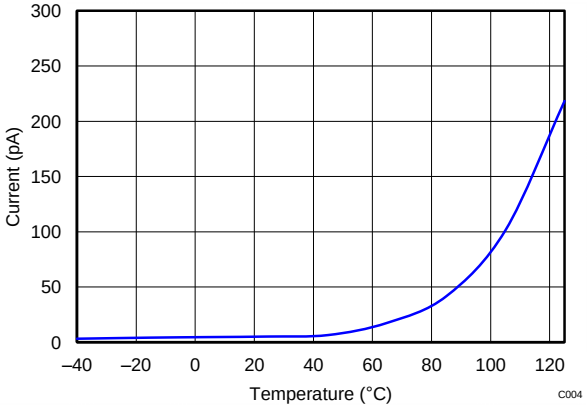


Figure 5. Leakage vs Temperature

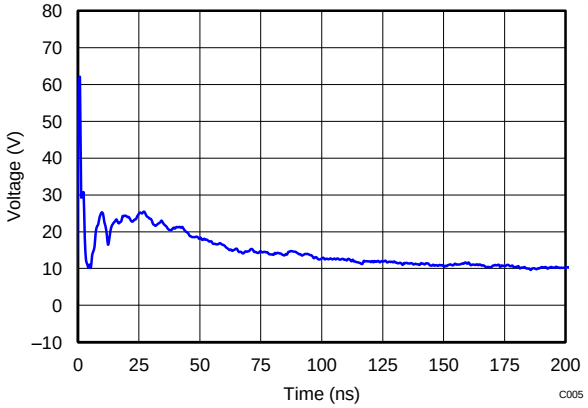


Figure 6. 8-kV IEC Waveform

Typical Characteristics (continued)

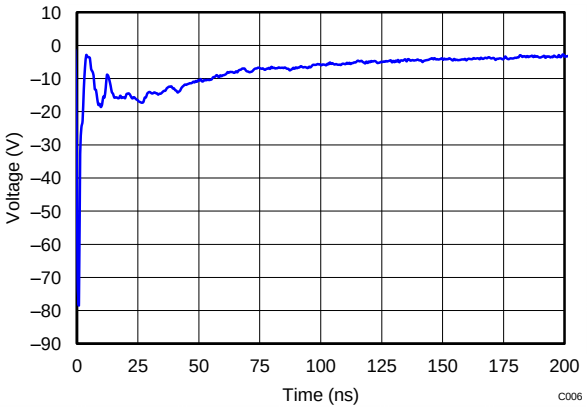


Figure 7. –8-kV IEC Waveform

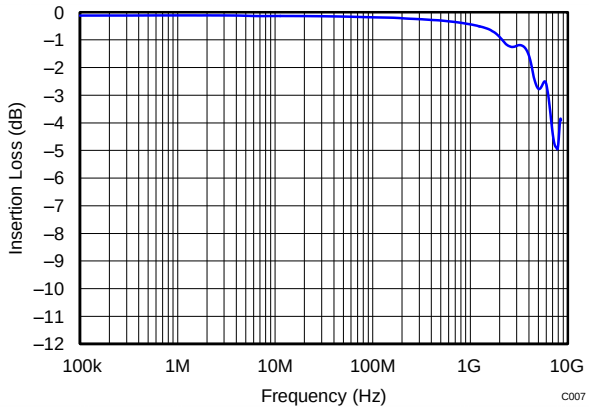


Figure 8. TPD1E05U06 Insertion Loss

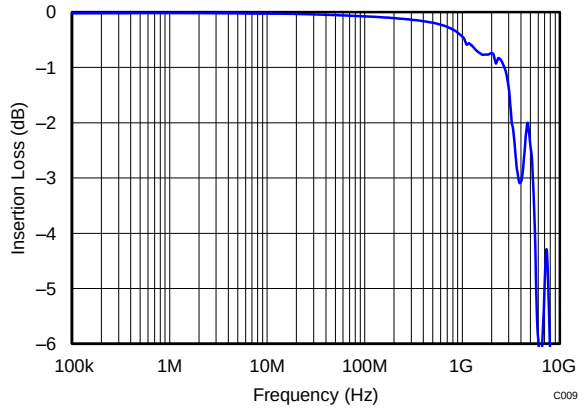


Figure 9. TPD4E05U06 Insertion Loss

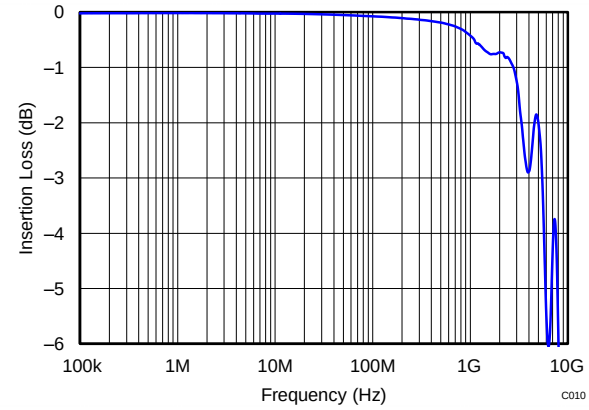


Figure 10. TPD6E05U06 Insertion Loss

7 Detailed Description

7.1 Overview

The TPDxE05U06 is a family of unidirectional Transient Voltage Suppressor (TVS) based Electrostatic Discharge (ESD) protection diodes with ultra-low capacitance. Each device can dissipate ESD strikes above the maximum level specified by the IEC 61000-4-2 international standard. The TPDxE05U06s ultra-low loading capacitance makes it ideal for protecting any high-speed signal pins.

7.2 Functional Block Diagram

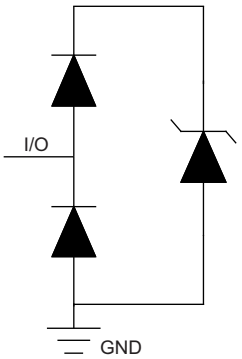


Figure 11. TPD1E05U06 Block Diagram

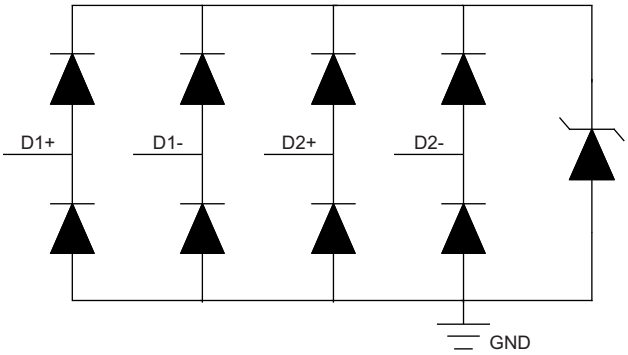


Figure 12. TPD4E05U06 Block Diagram

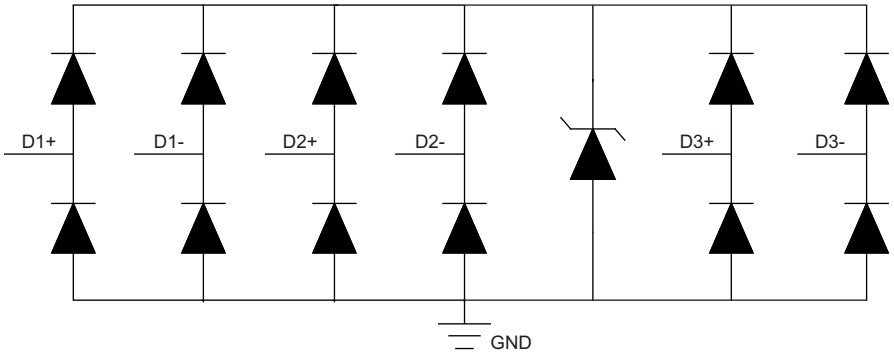


Figure 13. TPD6E05U06 Block Diagram

7.3 Feature Description

The TPDxE05U06 is a family of unidirectional Transient Voltage Suppressor (TVS) Electrostatic Discharge (ESD) protection diodes with ultra-low capacitance. Each device can dissipate ESD strikes above the maximum level specified by the IEC 61000-4-2 international standard. The TPDxE05U06s ultra-low loading capacitance makes it ideal for protecting any high-speed signal pins.

7.3.1 ±15-kV IEC61000-4-2 Level 4 ESD Protection

The I/O pins can withstand ESD events up to ±12-kV contact and ±15-kV air. An ESD-surge clamp diverts the current to ground.

7.3.2 IEC61000-4-4 EFT Protection

The I/O pins can withstand an electrical fast transient burst of up to 80 A (5/50 ns waveform, 4 kV with 50-Ω impedance). An ESD-surge clamp diverts the current to ground. This has been validated on the TPD4E05U06 only.

7.3.3 IEC61000-4-5 Surge Protection

The I/O pins can withstand surge events up to 2.5 A and 40 W (8/20 µs waveform). An ESD-surge clamp diverts this current to ground.

7.3.4 I/O Capacitance

The capacitance between each I/O pin to ground is 0.42 pF (TPD1E05U06), 0.5 pF (TPD4E05U06) or 0.47 pF (TPD6E05U06). These devices support data rates up to 6 Gbps.

7.3.5 DC Breakdown Voltage

The DC breakdown voltage of each I/O pin is a minimum of 6 V. This ensures that sensitive equipment is protected from surges above the reverse standoff voltage of 5 V.

7.3.6 Ultra-Low Leakage Current

The I/O pins feature an ultra-low leakage current of 10 nA (max) with a bias of 2.5 V.

7.3.7 Low ESD Clamping Voltage

The I/O pins feature an ESD clamp that is capable of clamping the voltage to 10 V (I_{PP} = 1 A).

7.3.8 Industrial Temperature Range

This device features an industrial operating range of –40°C to +125°C.

7.3.9 Easy Flow-Through Routing

The layout of this device makes it simple and easy to add protection to an existing layout. The packages offers flow-through routing, requiring minimal modification to an existing layout.

7.4 Device Functional Modes

The TPDxE05U06 is a passive integrated circuit that triggers when voltages are above VBR or below the lower diodes V_f (–0.6 V). During ESD events, voltages as high as ±15 kV (air) can be directed to ground via the internal diode network. When the voltages on the protected line fall below the trigger levels of TPDxE05U06 (usually within 10s of nano-seconds) the device reverts to passive.

8 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The TPDxE05U06 is a diode type TVS which is typically used to provide a path to ground for dissipating ESD events on hi-speed signal lines between a human interface connector and a system. As the current from ESD passes through the TVS, only a small voltage drop is present across the diode. This is the voltage presented to the protected IC. The low R_{DYN} of the triggered TVS holds this voltage, V_{CLAMP}, to a safe level for the protected IC.

8.2 Typical Applications

8.2.1 HDMI 2.0 Application

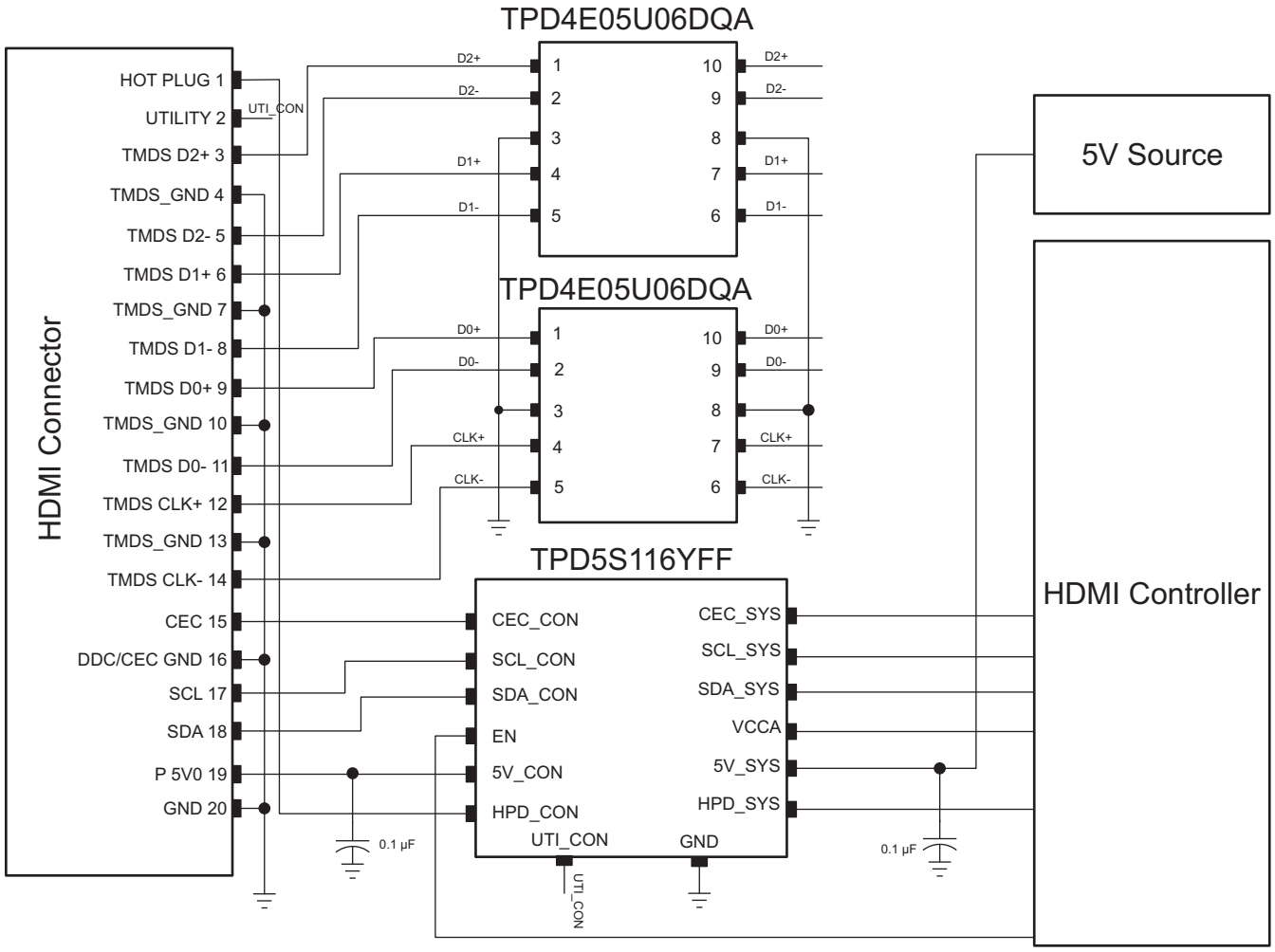


Figure 14. HDMI 2.0 Schematic

Typical Applications (continued)

8.2.1.1 Design Requirements

For this design example, the two TPD4E05U06 devices, and a TPD5S116 are being used in an HDMI 2.0 application. This provides a complete port protection scheme.

Given the HDMI 2.0 application, the parameters listed in Table 1 are known.

Table 1. Design Parameters

DESIGN PARAMETER	VALUE
Signal range on pins 1, 2, 4, or 5	0 V to 5 V
Operating frequency	3 GHz

8.2.1.2 Detailed Design Procedure

8.2.1.2.1 Signal Range on Pin 1, 2, 4, or 5

The TPD4E05U06 has 4 identical protection channels for signal lines. The symmetry of the device provides flexibility when selecting which of the 4 I/O channels is going to protect which signal lines. Any I/O supports a signal range of 0 to 5.5 V.

8.2.1.3 Application Curves

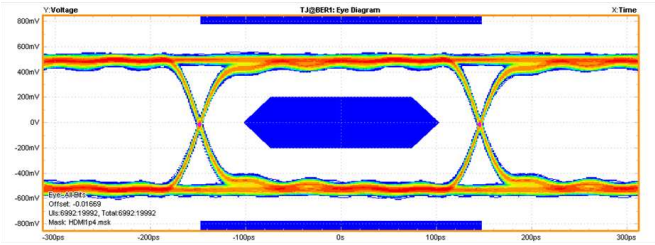


Figure 15. 3.4-Gbps HDMI 1.4 TP1 Eye Diagram Unpopulated EVM

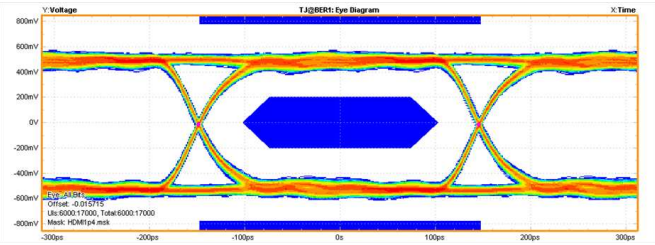


Figure 16. 3.4-Gbps HDMI 1.4 TP1 Eye Diagram TPD1E05U06

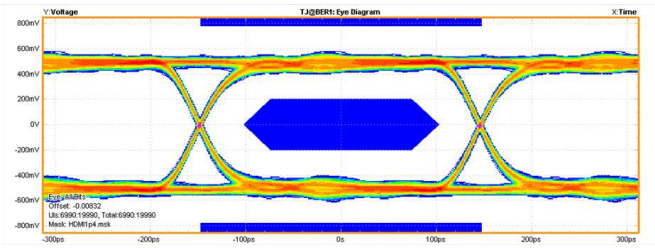


Figure 17. 3.4-Gbps HDMI 1.4 TP1 Eye Diagram TPD4E05U06

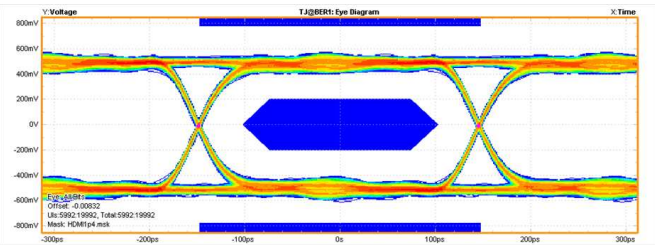


Figure 18. 3.4-Gbps HDMI 1.4 TP1 Eye Diagram TPD6E05U06

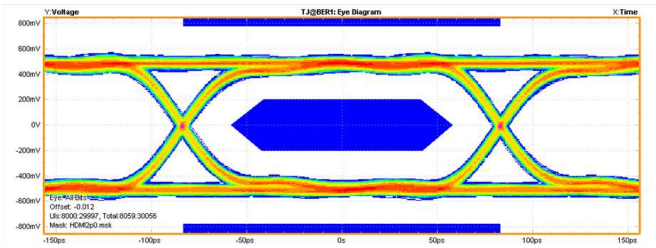


Figure 19. 6-Gbps HDMI 2.0 (TP1) Eye Diagram Unpopulated EVM

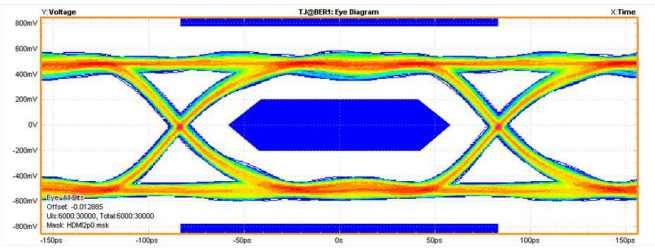


Figure 20. 6-Gbps HDMI 2.0 (TP1) Eye Diagram TPD1E05U06

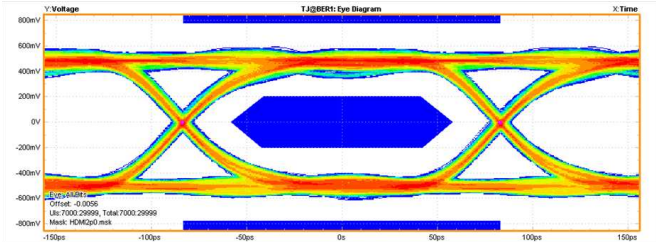


Figure 21. 6-Gbps HDMI 2.0 (TP1) Eye Diagram TPD4E05U06

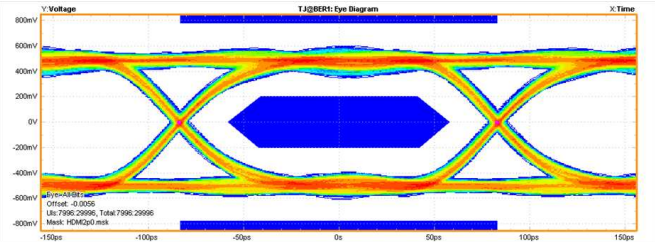


Figure 22. 6-Gbps HDMI 2.0 (TP1) Eye Diagram TPD6E05U06

8.2.2 HDMI 2.0 Application

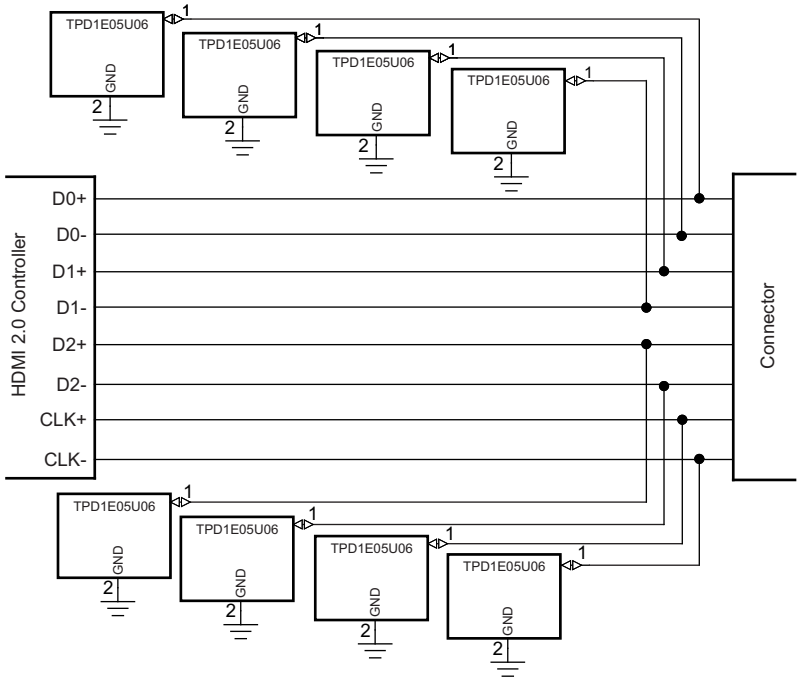


Figure 23. HDMI 2.0 Schematic

8.2.2.1 Design Requirements

For this design example, the TPD1E05U06 and the TPD5S116 are used to protect the data pairs and control lines of the HDMI 2.0 connection. This provides full HDMI 2.0 port protection.

Given the HDMI 2.0 application, the following parameters in Table 2 are known.

Table 2. Design Parameters

DESIGN PARAMETER	VALUE
Signal range on data lines	0 V to 5 V
Operating frequency	3 GHz

8.2.2.2 Detailed Design Procedure

8.2.2.2.1 Signal Range

The TPD1E05U06 has 1 protection channel for signal lines, supporting a signal range of 0 V to 5.5 V.

8.2.2.2.2 Operating Frequency

The TPD1E05U06 has 0.42 pF of capacitance, which supports HDMI 2.0 data rates.

8.2.2.3 Application Curves

Refer to the *Application Curves* section.

9 Power Supply Recommendations

This device is a passive ESD protection device and there is no need to power it. Care must be taken to make sure that the maximum voltage specifications for each line are not violated.

10 Layout

10.1 Layout Guidelines

- The optimum placement is as close to the connector as possible.
  - EMI during an ESD event can couple from the trace being struck to other nearby unprotected traces, resulting in early system failures.
  - The PCB designer needs to minimize the possibility of EMI coupling by keeping any unprotected traces away from the protected traces which are between the TVS and the connector.
- Route the protected traces as straight as possible.
- Eliminate any sharp corners on the protected traces between the TVS and the connector by using rounded corners with the largest radii possible.
  - Electric fields tend to build up on corners, increasing EMI coupling.

10.2 Layout Example

10.2.1 TPD4E05U06 Layout Example

This application is typical of an HDMI 1.4 layout.

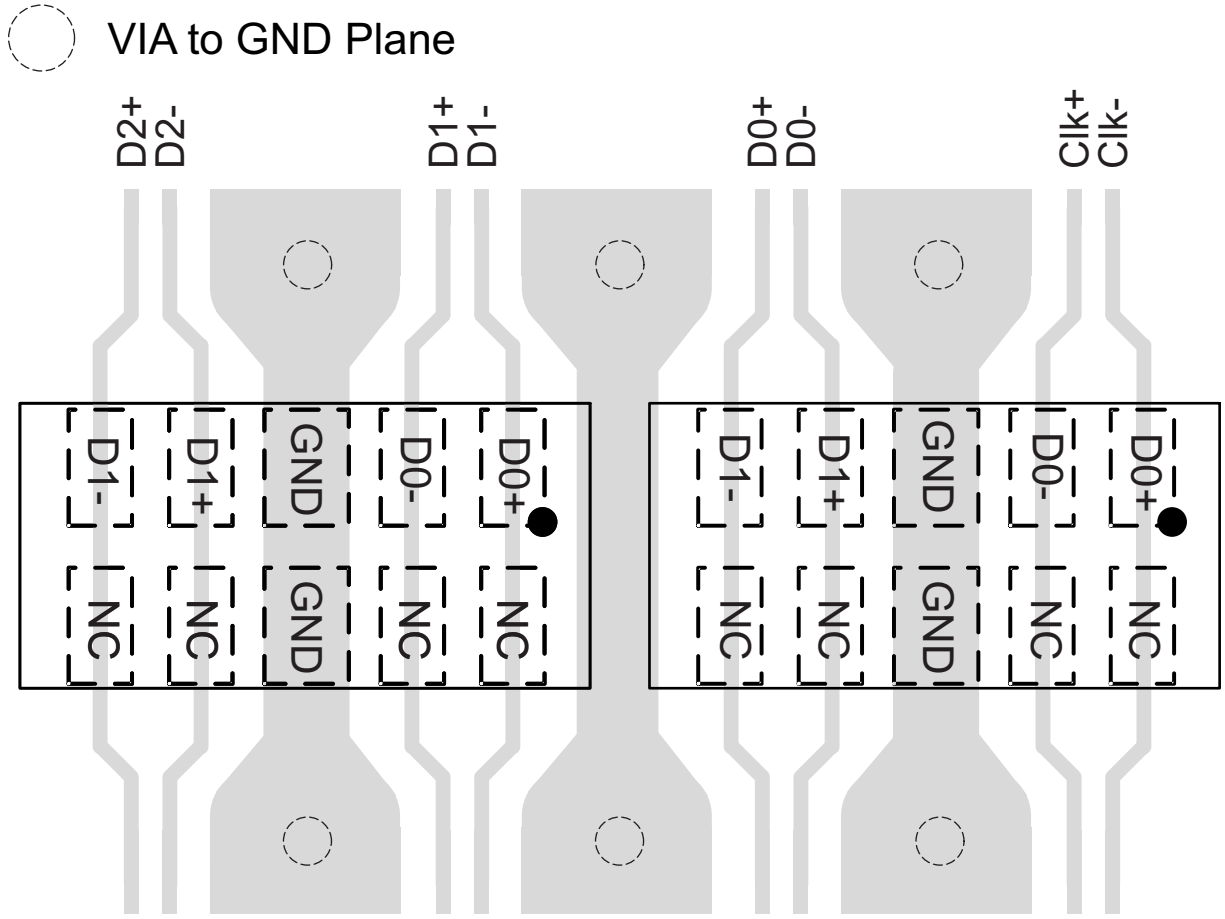


Figure 24. TPD4E05U06 Layout

Layout Example (continued)

10.2.2 TPD1E05U06 Layout Example

This application is typical of an HDMI 2.0 layout.

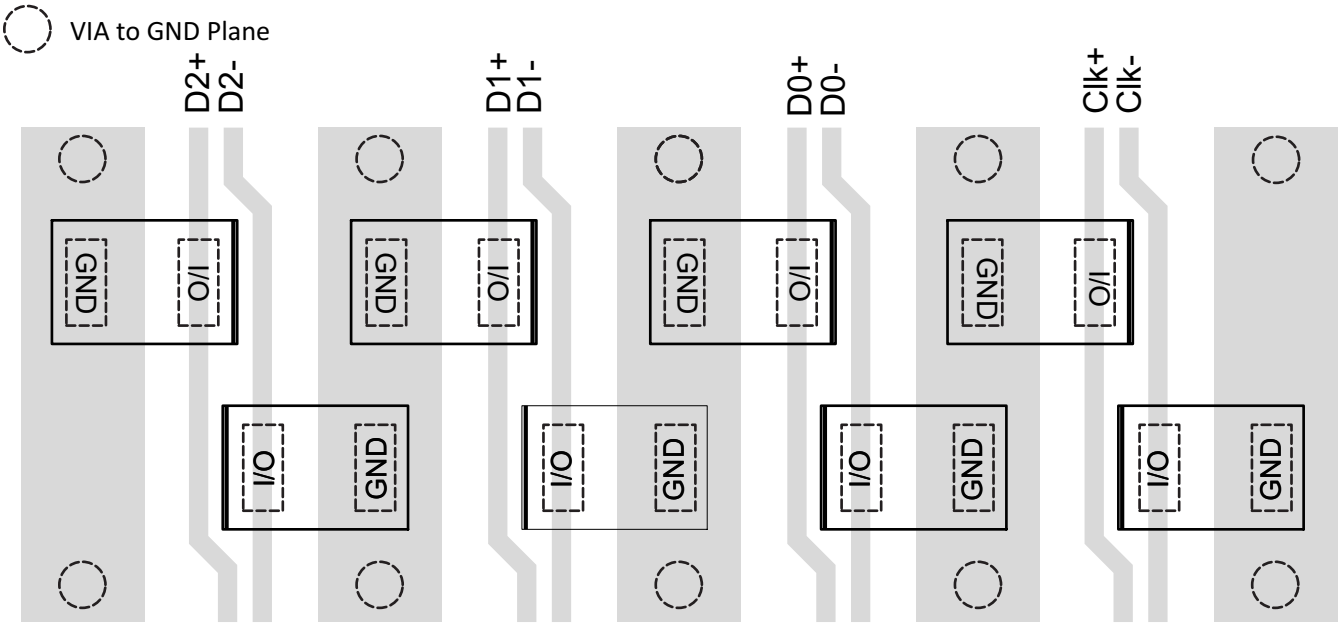


Figure 25. TPD1E05U06 Layout

11 器件和文档支持

11.1 文档支持

11.1.1 相关文档

相关文档如下：

- *阅读和理解 ESD 保护数据表*
- *《ESD 布局指南》*
- *《TPD6E05U06RVZ GUI 用户指南》*
- *《为超高速数据线选择 ESD 二极管》*
- *《ESD 保护二极管 EVM》*
- *《TPD1E05U06DPY GUI 用户指南》*
- *《TPD4E05U06DQA GUI 用户指南》*

11.2 相关链接

以下表格列出了快速访问链接。范围包括技术文档、支持与社区资源、工具和软件，并且可以快速访问样片或购买链接。

表 **3.** 相关链接

器件	产品文件夹	样片与购买	技术文档	工具与软件	支持与社区
TPD1E05U06	请单击此处	请单击此处	请单击此处	请单击此处	请单击此处
TPD4E05U06	请单击此处	请单击此处	请单击此处	请单击此处	请单击此处
TPD6E05U06	请单击此处	请单击此处	请单击此处	请单击此处	请单击此处

11.3 接收文档更新通知

要接收文档更新通知（包括芯片勘误表），请转至 ti.com.cn 上您的器件对应的产品文件夹。单击右上角的*“提醒我”(Alert me)* 按钮。点击后，您将每周定期收到已更改的产品信息（如果有的话）。有关更改的详细信息，请查阅已修订文档的修订历史记录。

11.4 社区资源

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E™ Online Community ***TI's Engineer-to-Engineer (E2E) Community.*** Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support ***TI's Design Support*** Quickly find helpful E2E forums along with design support tools and contact information for technical support.

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11.6 静电放电警告

这些装置包含有限的内置 ESD 保护。 存储或装卸时，应将导线一起截短或将装置放置于导电泡棉中，以防止 MOS 门极遭受静电损伤。

11.7 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

12 机械、封装和可订购信息

以下页中包括机械、封装和可订购信息。这些信息是针对指定器件可提供的最新数据。这些数据会在无通知且不对本文档进行修订的情况下发生改变。欲获得该数据表的浏览器版本，请查阅左侧的导航栏。

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPD1E05U06DPYR	ACTIVE	X1SON	DPY	2	10000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	(C1 ~ C6)	Samples
TPD1E05U06DPYT	ACTIVE	X1SON	DPY	2	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	(C1 ~ C6)	Samples
TPD4E05U06DQAR	ACTIVE	USON	DQA	10	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	BR BRY	Samples
TPD6E05U06RVZR	ACTIVE	USON	RVZ	14	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	(BV ~ BVY)	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

OTHER QUALIFIED VERSIONS OF TPD4E05U06 :

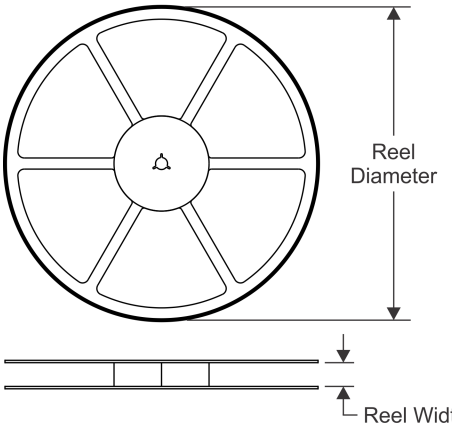
- Automotive: TPD4E05U06-Q1

NOTE: Qualified Version Definitions:

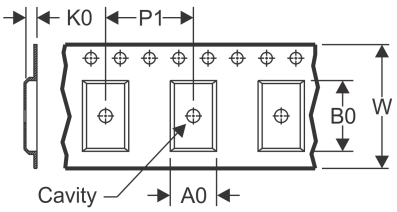
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION

REEL DIMENSIONS

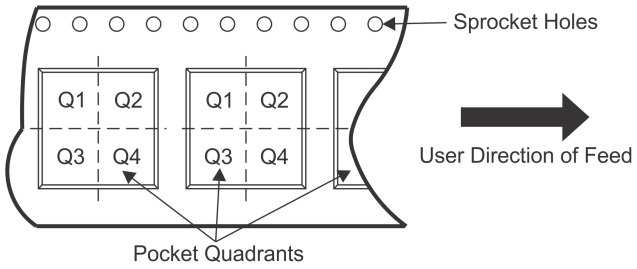


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

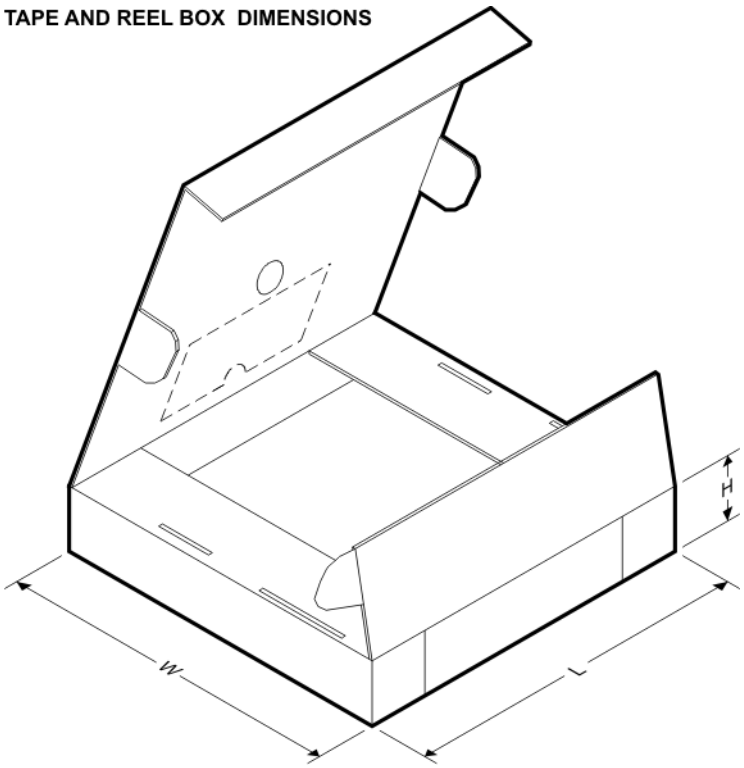
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPD1E05U06DPYR	X1SON	DPY	2	10000	180.0	9.5	0.66	1.15	0.66	2.0	8.0	Q1
TPD1E05U06DPYT	X1SON	DPY	2	250	180.0	9.5	0.72	1.12	0.43	2.0	8.0	Q1
TPD1E05U06DPYT	X1SON	DPY	2	250	180.0	9.5	0.66	1.15	0.66	2.0	8.0	Q1
TPD4E05U06DQAR	USON	DQA	10	3000	180.0	9.5	1.18	2.68	0.72	4.0	8.0	Q1
TPD6E05U06RVZR	USON	RVZ	14	3000	178.0	13.5	1.6	3.75	0.7	4.0	12.0	Q1
TPD6E05U06RVZR	USON	RVZ	14	3000	180.0	13.2	1.65	3.8	0.7	4.0	12.0	Q1

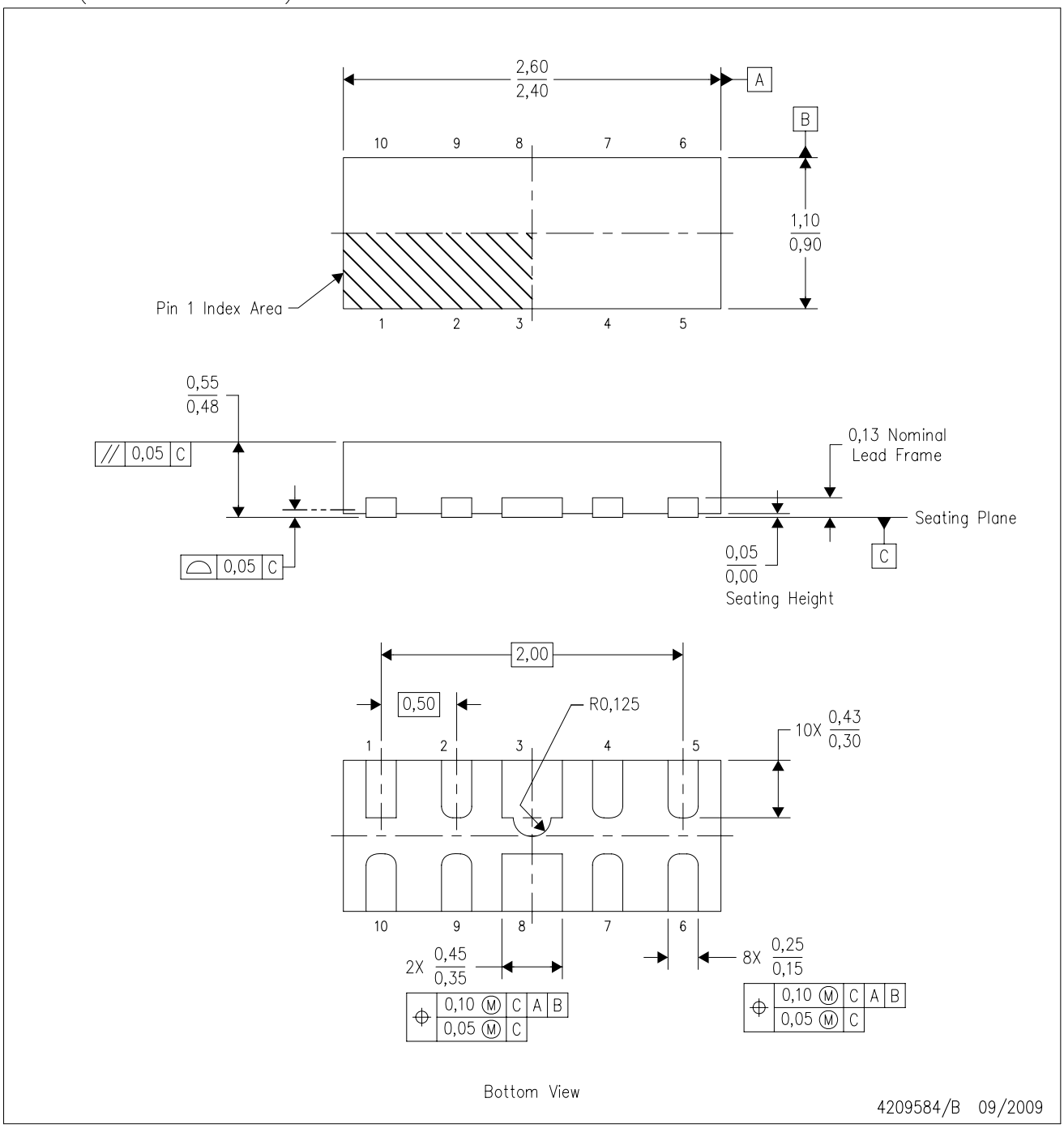
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

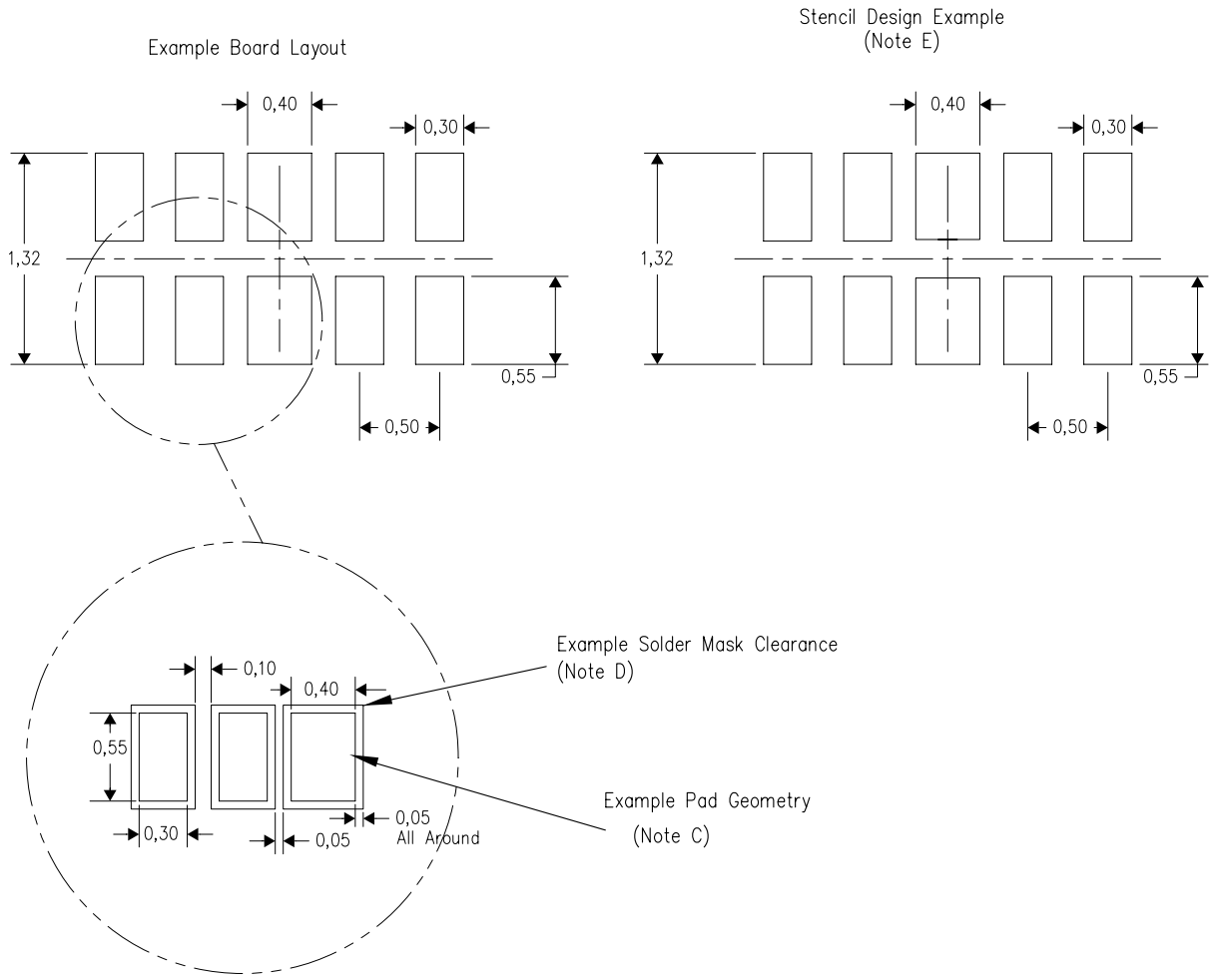
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPD1E05U06DPYR	X1SON	DPY	2	10000	184.0	184.0	19.0
TPD1E05U06DPYT	X1SON	DPY	2	250	189.0	185.0	36.0
TPD1E05U06DPYT	X1SON	DPY	2	250	184.0	184.0	19.0
TPD4E05U06DQAR	USON	DQA	10	3000	189.0	185.0	36.0
TPD6E05U06RVZR	USON	RVZ	14	3000	189.0	185.0	36.0
TPD6E05U06RVZR	USON	RVZ	14	3000	184.0	184.0	19.0

DQA (R–PSON–N10) PLASTIC SMALL OUTLINE NO–LEAD



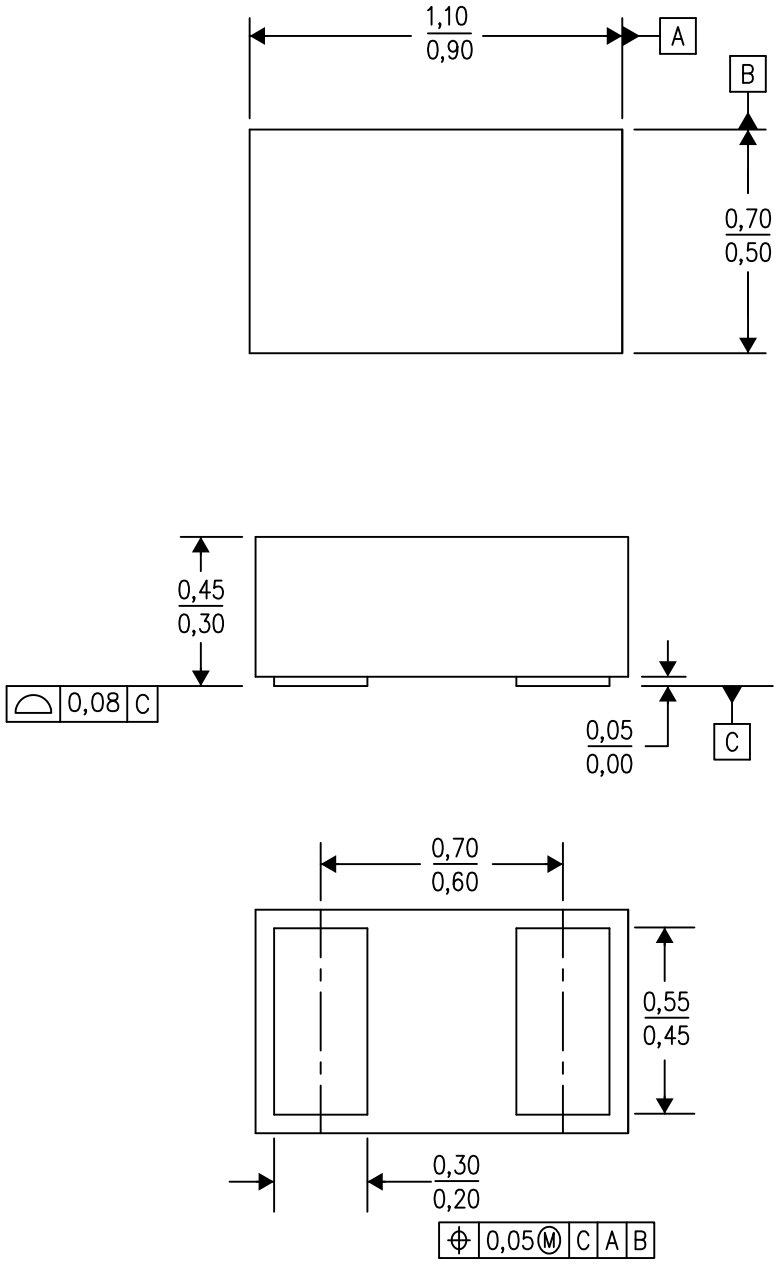
NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. SON (Small Outline No–Lead) package configuration.

DQA (R–PUSON–N10) PLASTIC SMALL OUTLINE NO–LEAD



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.
E. Maximum stencil thickness 0,127 mm (5 mils). All linear dimensions are in millimeters.
F. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
G. Side aperture dimensions over–print land for acceptable area ratio > 0.66. Customer may reduce side aperture dimensions if stencil manufacturing process allows for sufficient release at smaller opening.

DPY (R–PX1SON–N2) PLASTIC SMALL OUTLINE NO–LEAD



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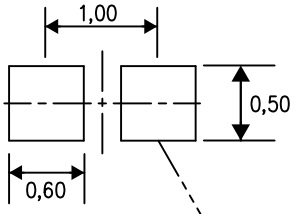
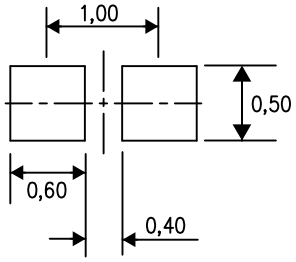
NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5–1994.
B. This drawing is subject to change without notice.
C. SON (Small Outline No–Lead) package configuration.

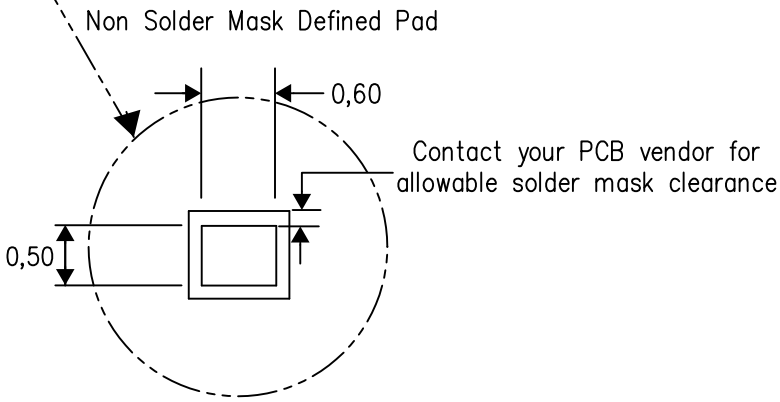
DPY (R–PX1SON–N2) PLASTIC SMALL OUTLINE NO–LEAD

Example Board Layout



Example Stencil Design
(Note E)

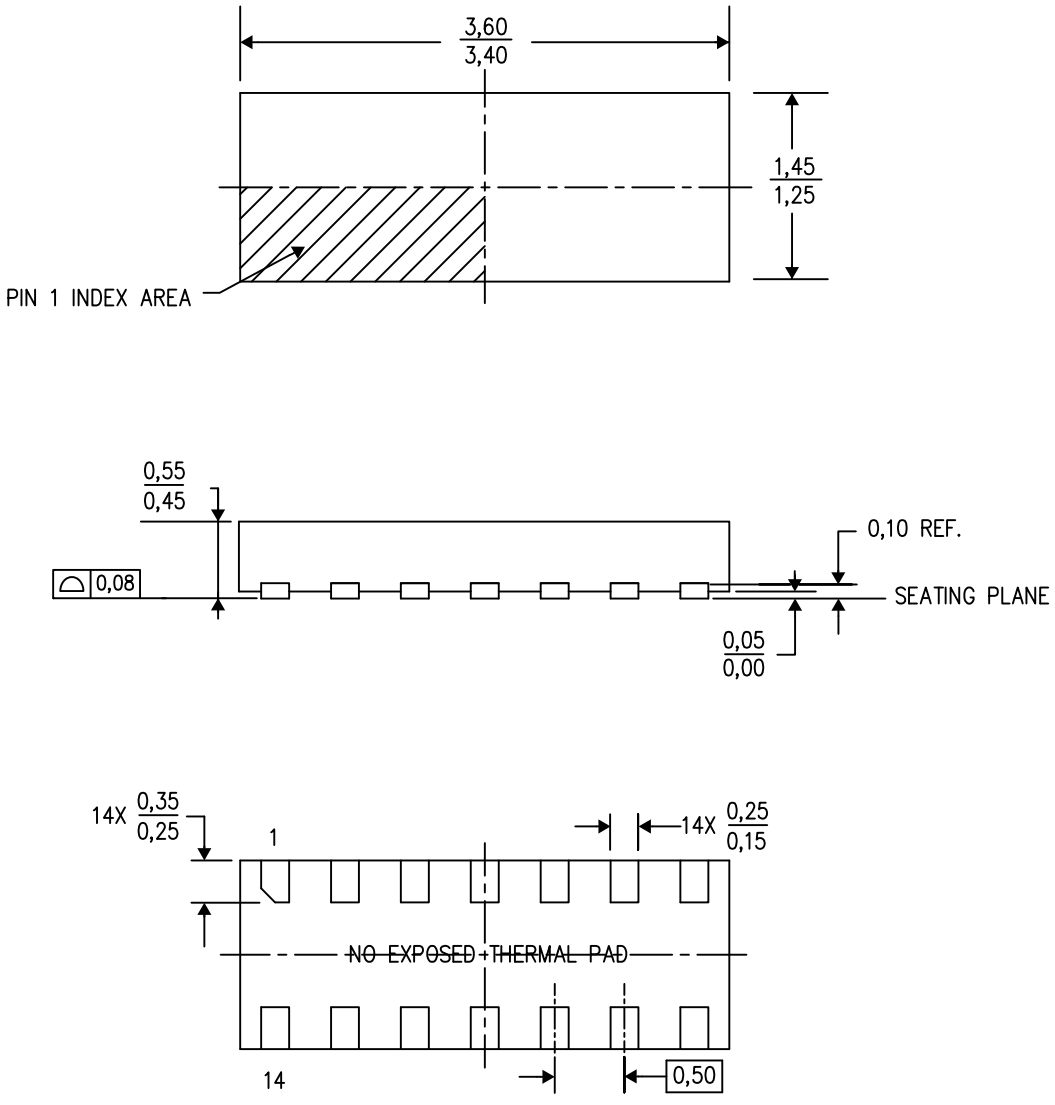




4215270/B 08/15

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.
E. Maximum stencil thickness 0,127 mm (5 mils). All linear dimensions are in millimeters.
F. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
G. Side aperture dimensions over–print land for acceptable area ratio > 0.66. Customer may reduce side aperture dimensions if stencil manufacturing process allows for sufficient release at smaller opening.

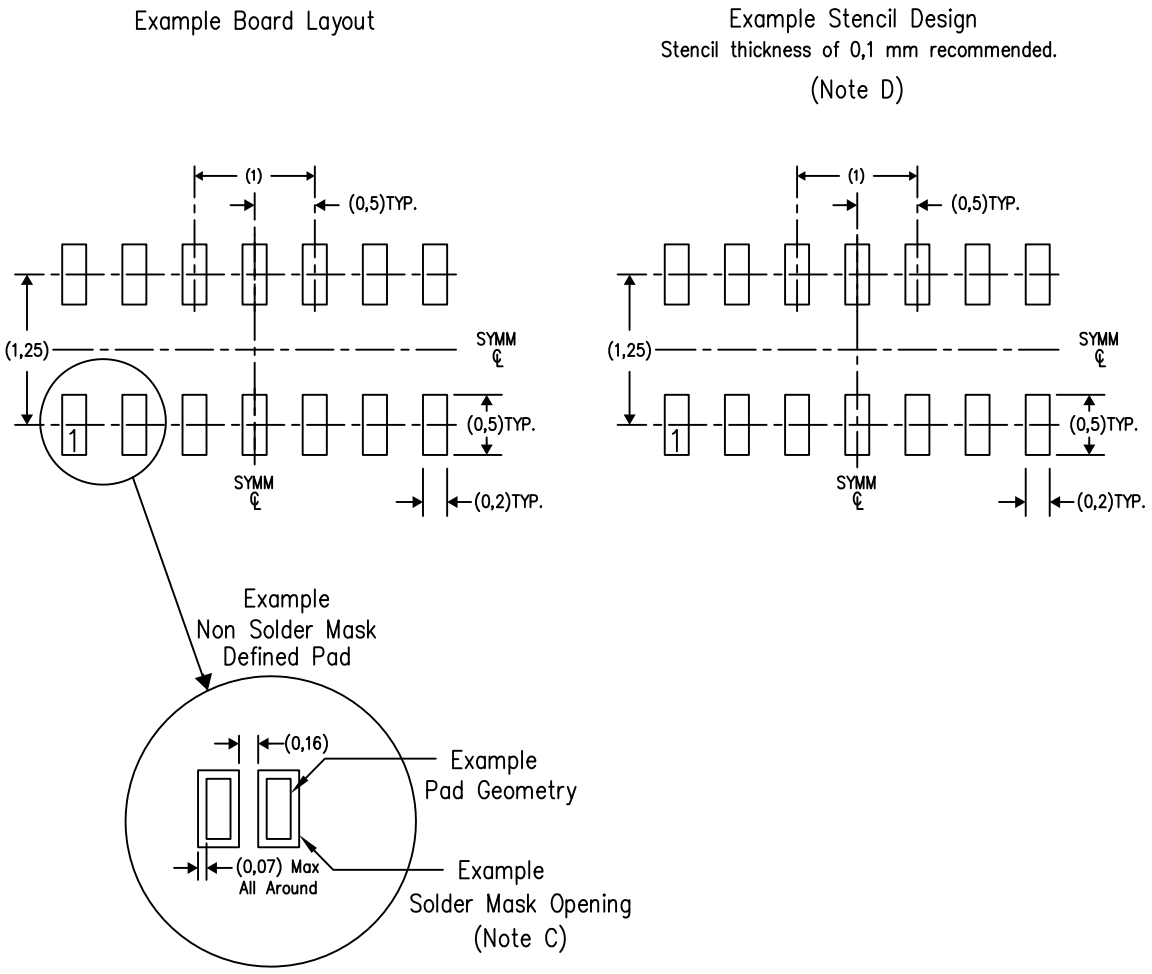
RVZ (R–PUSON–N14) PLASTIC SMALL OUTLINE NO–LEAD



4218112/B 04/14

NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. QFN (Quad Flatpack No–Lead) package configuration.

RVZ (R–PUSON–N14) PLASTIC SMALL OUTLINE NO–LEAD



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.

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